

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 08/27/2022

Details for "ISO7240CDWG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
ISO7240CDWG4	NIPDAU	Level-2-260C-1 YEAR	TI TAIWAN A/T	DW 16	7.52x10.28x2.35	633.8

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Iron	7439-89-6	0.00002	0.000243	2	0	0
Other Nonferrous Metals and Alloys	Beryllium	7440-41-7	0.00001	0.000121	1	0	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.00002	0.000243	2	0	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.00006	0.000729	7	0.000001	0
Precious Metals	Gold	7440-57-5	0.823357	99.997571	999976	0.129918	1299
Precious Metals	Silver	7440-22-4	0.000009	0.001093	11	0.000001	0
Sub-Total			0.823377	100	1000000	0.129921	1299
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.304044	75	750000	0.047975	480
Thermoplastics	Epoxy	85954-11-6	0.101348	25	250000	0.015992	160
Sub-Total			0.405392	100	1000000	0.063967	640
Die Attach Adhesive 2							
Precious Metals	Silver	7440-22-4	0.463447	75.00004	750000	0.073127	731
Thermoplastics	Epoxy	85954-11-6	0.154482	24.99996	250000	0.024376	244
Sub-Total			0.617929	100	1000000	0.097503	975
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	272.06698	97.585	975850	42.929528	429295
Copper and Its Alloys	Iron	7439-89-6	6.4124	2.3	23000	1.011814	10118
Copper and Its Alloys	Phosphorus	7723-14-0	0.04182	0.015	150	0.006599	66
Zinc and Its Alloys	Zinc	7440-66-6	0.2788	0.1	1000	0.043992	440
Sub-Total			278.8	100	1000000	43.991933	439919
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.279364	95.12	951200	0.201871	2019
Precious Metals	Gold	7440-57-5	0.010491	0.78	7800	0.001655	17
Precious Metals	Palladium	7440-05-3	0.055145	4.1	41000	0.008701	87
Sub-Total			1.345	100	1000000	0.212228	2122
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	299.298796	86	860000	47.226444	472264
Other Plastics and Rubber	Carbon Black	1333-86-4	1.044066	0.3	3000	0.164743	1647
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	1.91412	0.55	5500	0.30203	3020
Thermoplastics	Epoxy	85954-11-6	45.764874	13.15	131500	7.221253	72213
Sub-Total			348.021856	100	1000000	54.91447	549145
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.481215	100	1000000	0.233721	2337
Sub-Total			1.481215	100	1000000	0.233721	2337
Semiconductor Device 2							
Ceramics / Glass	Doped Silicon	7440-21-3	2.257783	100	1000000	0.356256	3563
Sub-Total			2.257783	100	1000000	0.356256	3563
Total			633.752552			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet I5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.